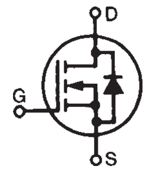
GigaMOS™ TrenchT2 HiperFET™ Power MOSFET

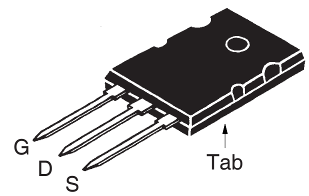
IXFK220N17T2
IXFX220N17T2

V_{DSS}	=	170V
I_{D25}	=	220A
$R_{DS(on)}$	≤	6.3mΩ
t_{rr}	≤	140ns

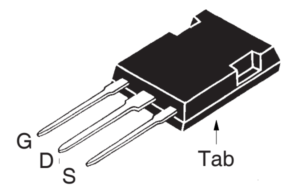
N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode



TO-264 (IXFK)



PLUS247 (IXFX)



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 175°C	170	V
V_{DGR}	T_J = 25°C to 175°C, R_{GS} = 1MΩ	170	V
V_{GSS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	T_C = 25°C (Chip Capability)	220	A
$I_{L(RMS)}$	External Lead Current Limit	160	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	550	A
I_A	T_C = 25°C	110	A
E_{AS}	T_C = 25°C	2	J
P_D	T_C = 25°C	1250	W
dv/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 175°C$	20	V/ns
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +175	°C
T_L	1.6mm (0.062 in.) from Case for 10s	300	°C
T_{SOLD}	Plastic Body for 10s	260	°C
M_d	Mounting Torque (TO-264)	1.13/10	Nm/lb.in.
F_C	Mounting Force (PLUS247)	20..120 /4.5..27	N/lb.
Weight	TO-264	10	g
	PLUS247	6	g

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 3mA	170			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 8mA	2.5		5.0	V
I_{GSS}	V_{GS} = ± 20V, V_{DS} = 0V			± 200	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS}= 0V			25	μA
	T_J = 150°C			3	mA
$R_{DS(on)}$	V_{GS} = 10V, I_D = 60A, Note 1		5.1	6.3	mΩ

Features

- High Current Handling Capability
- Fast Intrinsic Diode
- Avalanche Rated
- Low $R_{DS(on)}$

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- Synchronous Recification
- DC-DC Converters
- Battery Chargers
- Switch-Mode and Resonant-Mode Power Supplies
- DC Choppers
- AC Motor Drives
- Uninterruptible Power Supplies
- High Speed Power Switching Applications

Symbol	Test Conditions ($T_J = 25°C$ Unless Otherwise Specified)	Min.	Typ.	Max.	
g_{fs}	$V_{DS} = 10V$, $I_D = 60A$, Note 1	105	175		S
C_{iss}	$V_{GS} = 0V$, $V_{DS} = 25V$, f = 1MHz		31		nF
C_{oss}			2130		pF
C_{rss}			290		pF
R_{Gi}	Gate Input Resistance		1.40		Ω
$t_{d(on)}$	**Resistive Switching Times** $V_{GS} = 10V$, $V_{DS} = 0.5 \bullet V_{DSS}$, $I_D = 0.5 \bullet I_{D25}$ $R_G = 1\Omega$ (External)		44		ns
t_r			160		ns
$t_{d(off)}$			40		ns
t_f			150		ns
$Q_{g(on)}$	$V_{GS} = 10V$, $V_{DS} = 0.5 \bullet V_{DSS}$, $I_D = 0.5 \bullet I_{D25}$		500		nC
Q_{gs}			130		nC
Q_{gd}			137		nC
R_{thJC}				0.12	°C/W
R_{thCS}			0.15		°C/W

Source-Drain Diode

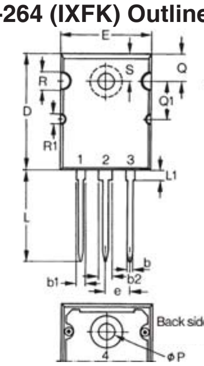
Symbol	Test Conditions ($T_J = 25°C$, Unless Otherwise Specified)	Min.	Typ.	Max.	
I_S	$V_{GS} = 0V$			220	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			880	A
V_{SD}	$I_F = 100A$, $V_{GS} = 0V$, Note 1			1.3	V
t_{rr}	$I_F = 110A$, -di/dt = 100A/μs $V_R = 85V$, $V_{GS} = 0V$			140	ns
Q_{RM}			0.5		μC
I_{RM}			8.6		A

Note 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

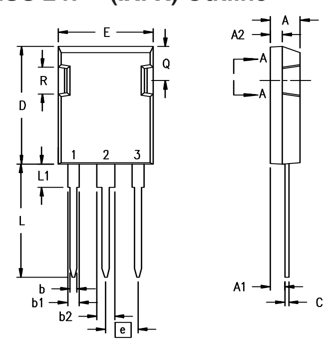
TO-264 (IXFK) Outline



Terminals: 1 - Gate
2 - Drain
3 - Source

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.82	5.13	.190	.202
A1	2.54	2.89	.100	.114
A2	2.00	2.10	.079	.083
b	1.12	1.42	.044	.056
b1	2.39	2.69	.094	.106
b2	2.90	3.09	.114	.122
c	0.53	0.83	.021	.033
D	25.91	26.16	1.020	1.030
E	19.81	19.96	.780	.786
e	5.46 BSC		.215 BSC	
J	0.00	0.25	.000	.010
K	0.00	0.25	.000	.010
L	20.32	20.83	.800	.820
L1	2.29	2.59	.090	.102
P	3.17	3.66	.125	.144
Q	6.07	6.27	.239	.247
Q1	8.38	8.69	.330	.342
R	3.81	4.32	.150	.170
R1	1.78	2.29	.070	.090
S	6.04	6.30	.238	.248
T	1.57	1.83	.062	.072

PLUS 247™ (IXFX) Outline



Terminals: 1 - Gate
2 - Drain
3 - Source

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.83	5.21	.190	.205
A_1	2.29	2.54	.090	.100
A_2	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b_1	1.91	2.13	.075	.084
b_2	2.92	3.12	.115	.123
C	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
e	5.45 BSC		.215 BSC	
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	0.244
R	4.32	4.83	.170	.190

Fig. 1. Output Characteristics @ T_J = 25ºC

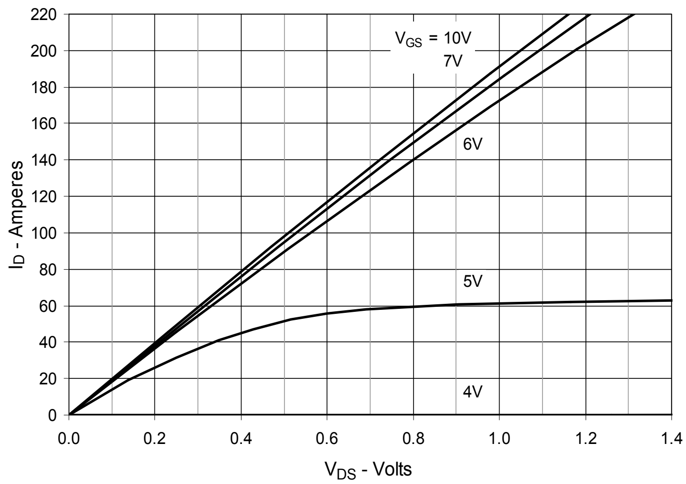


Fig. 2. Extended Output Characteristics @ T_J = 25ºC

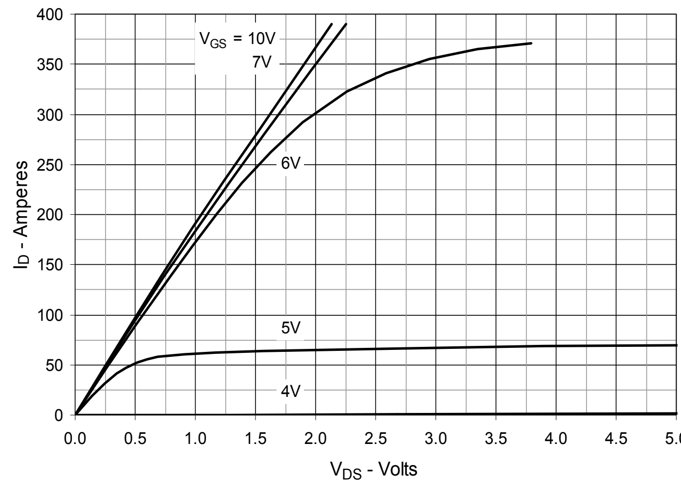


Fig. 3. Output Characteristics @ T_J = 150ºC

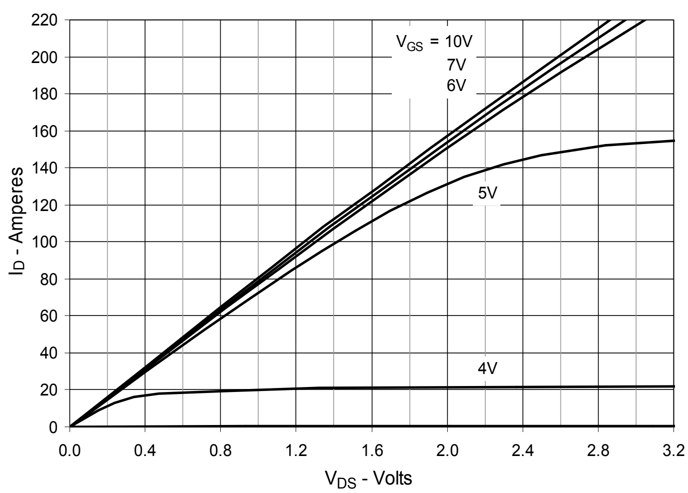


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 110A Value vs. Junction Temperature

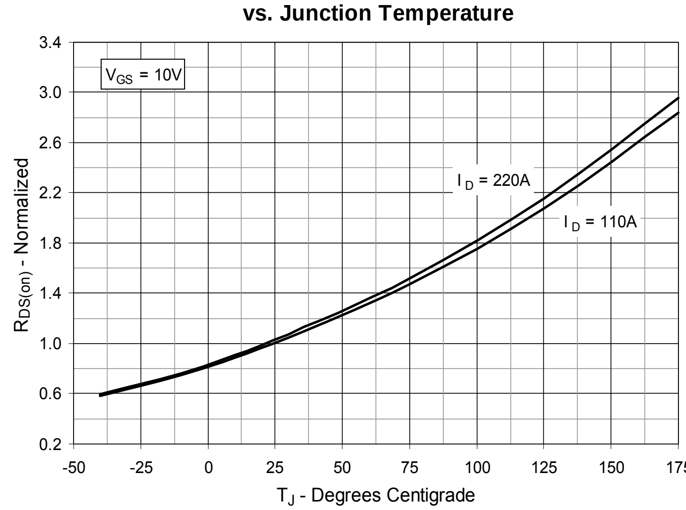


Fig. 5. Normalized $R_{DS(on)}$ I_D = 110A Value vs. Drain Current

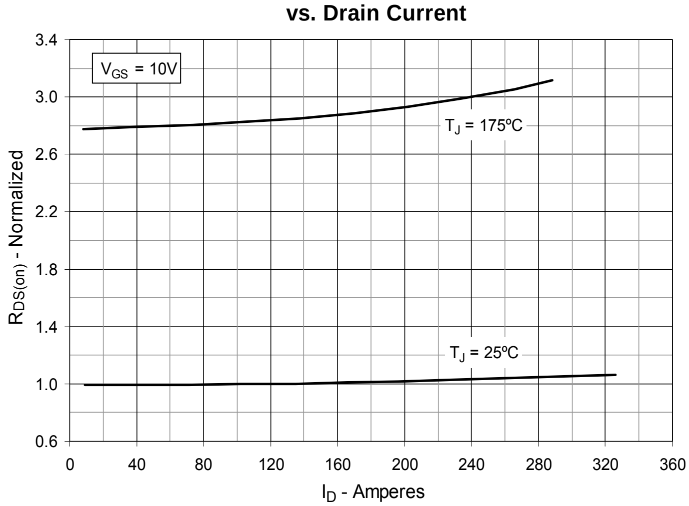


Fig. 6. Drain Current vs. Case Temperature

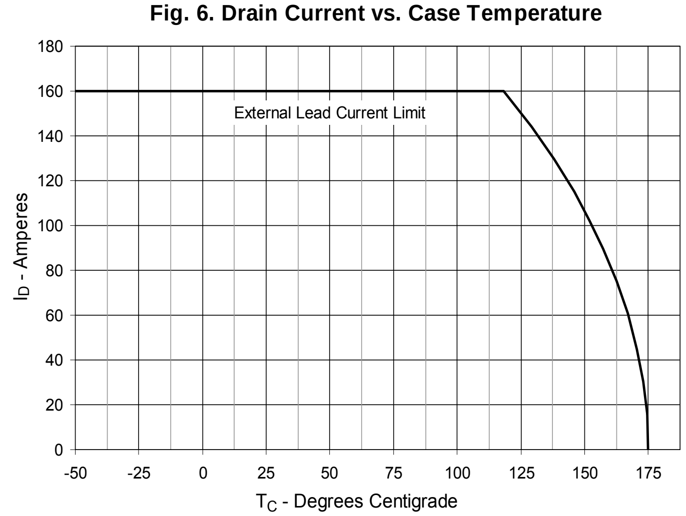


Fig. 7. Input Admittance

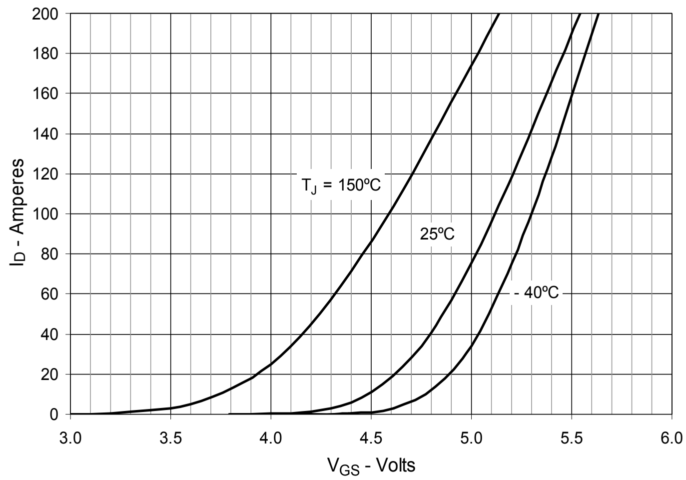


Fig. 8. Transconductance

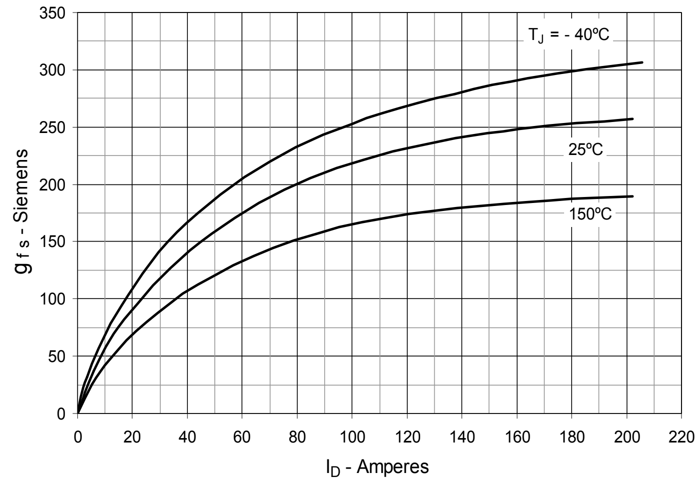


Fig. 9. Forward Voltage Drop of Intrinsic Diode

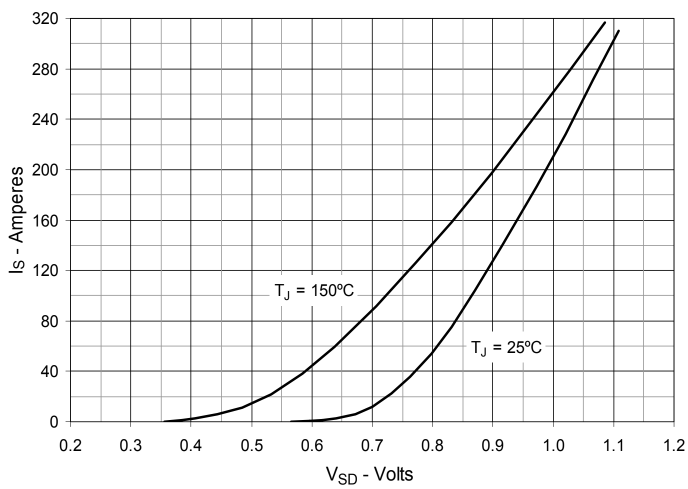


Fig. 10. Gate Charge

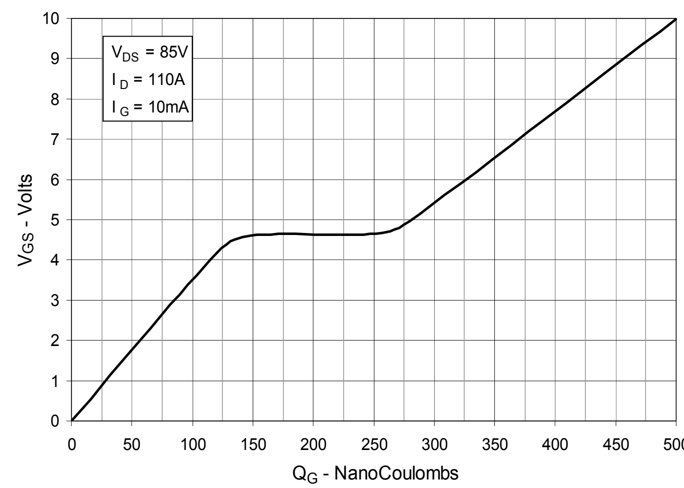


Fig. 11. Capacitance

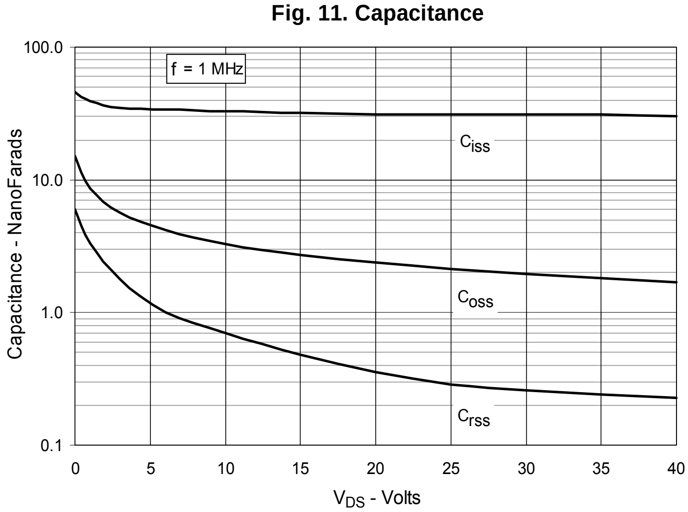


Fig. 12. Forward-Bias Safe Operating Area

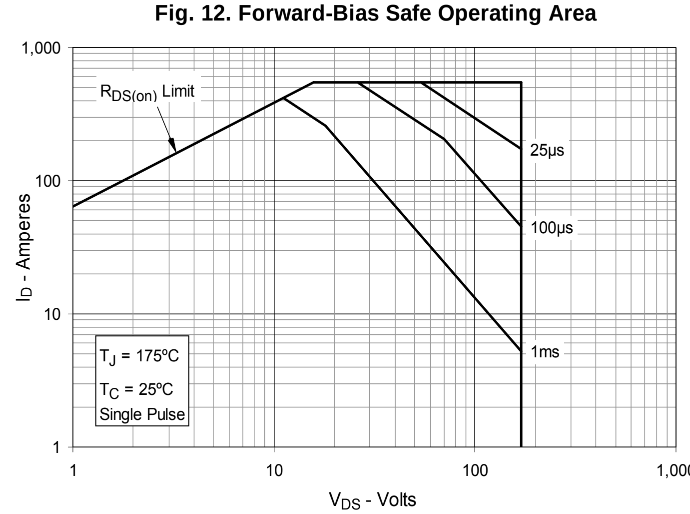


Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

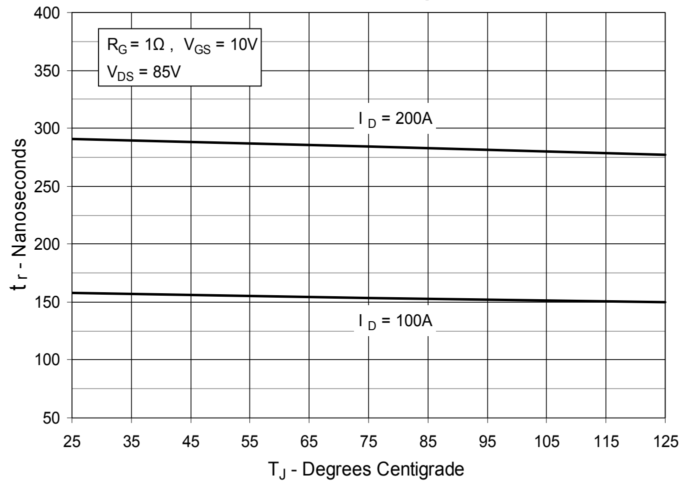


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

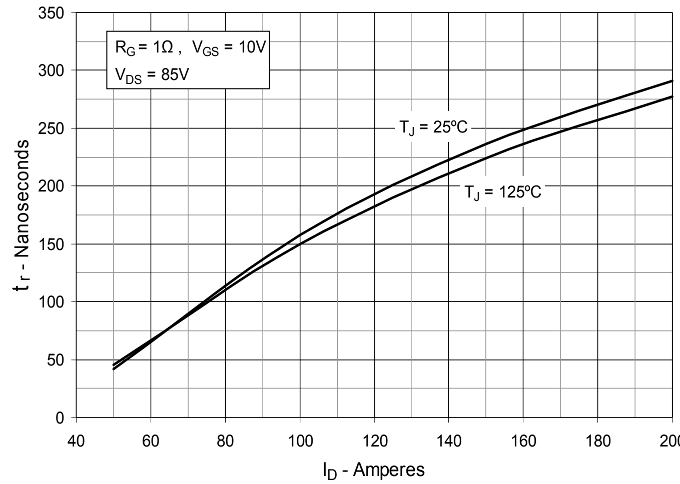


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

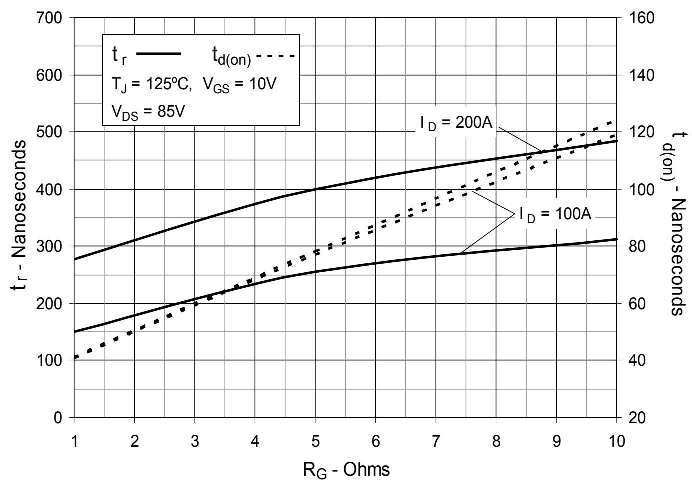


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

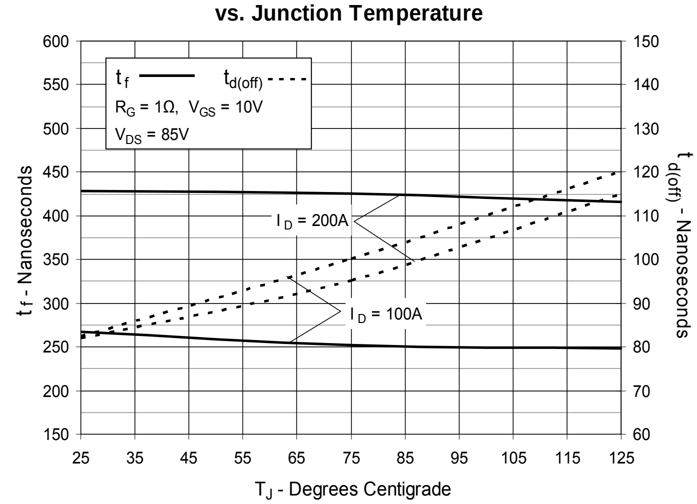


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

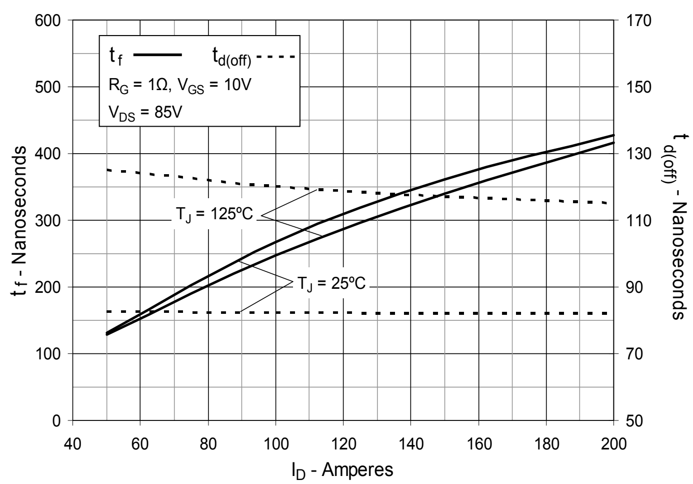


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance

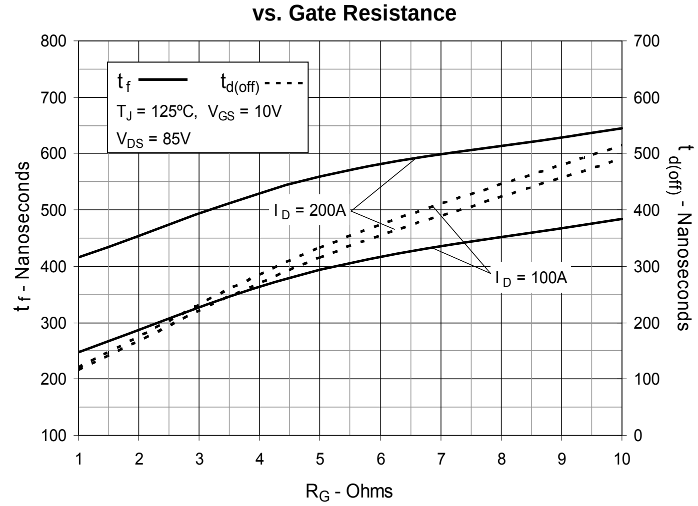
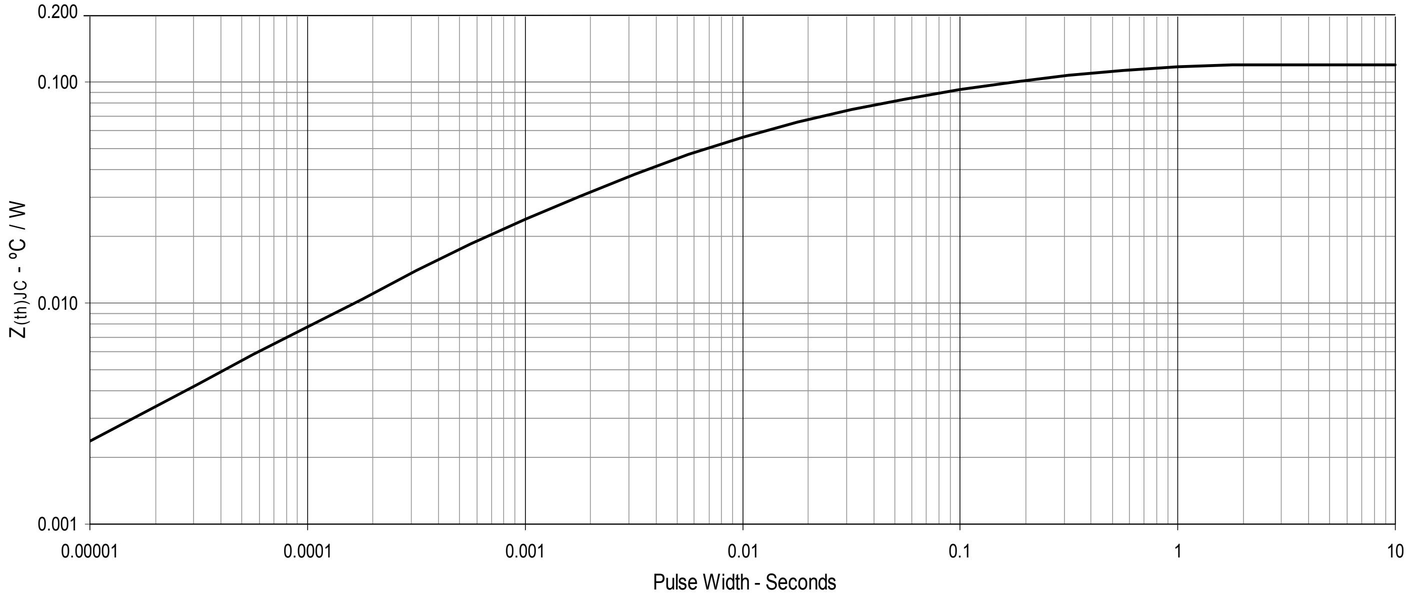


Fig. 19. Maximum Transient Thermal Impedance



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